

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	LIEN
CONVEYING PARTY DATA	
Name	Execution Date
GOKNOWN LLC	02/12/2020
RECEIVING PARTY DATA	
Name:	VAN DYKE INTELLECTUAL PROPERTY LAW
Street Address:	1050 CONNECTICUT AVENUE, NW
Internal Address:	WASHINGTON SQUARE, PO BOX 65302
City:	WASHINGTON, DC
State/Country:	D.C.
Postal Code:	20035
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17897901
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	12023783903
Email:	vandyke@acm.org
Correspondent Name:	RAYMOND VAN DYKE
Address Line 1:	1050 CONNECTICUT AVENUE, NW
Address Line 2:	WASHINGTON SQUARE, PO BOX 65302
Address Line 4:	WASHINGTON, DC, D.C. 20035
ATTORNEY DOCKET NUMBER:	HAROLD - LIEN
NAME OF SUBMITTER:	RAYMOND VAN DYKE
SIGNATURE:	/raymond van dyke/
DATE SIGNED:	02/13/2023
Total Attachments: 2	
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

AFFIDAVIT FOR PATENT LIEN
ON U.S. PATENTS AND PATENT APPLICATIONS
AND ALL PATENTS ISSUING THEREFROM

WHEREAS, I, Raymond Van Dyke of Van Dyke Intellectual Property Law (hereinafter designated as the undersigned) am the counsel for Applicant/Inventor GoKnown and Michael Harold (hereinafter designated as client);

WHEREAS the undersigned, at the behest of the client, prepared and filed a number of utility patent applications, obtained a number of patents therefrom, and advised the client on all matters IP, listed hereinbelow;

WHEREAS the client has numerous invoices unpaid for the patents and patent applications listed hereinbelow, with a total of at least \$18,260 owed as of the date of this document.

NOW THEREFORE, to all whom it may concern, be it known that the undersigned asserts sufficient financial interest in the subject matters of the below-identified patents and patents applications to obtain full payment of any and all amounts due and owing, establishes this lien over each case, which extends to all inventions and improvements disclosed in the aforesaid patent applications, and in and to the patents and patent applications, all divisions, continuations, continuations-in-part, or renewals thereof, all Letters Patent which may be granted therefrom, and all reissues or extensions of such patents, and in and to any and all applications which have been or shall be filed in any foreign countries for Letters Patent on the inventions and improvements, including any assignment of all rights under the provisions of the International Convention, and all Letters Patent of foreign countries which may be granted therefrom;

AND furthermore, the undersigned intends to take all necessary actions to make their financial interests in these patents and patent applications official in the records of the U.S. Patent & Trademark Office, and files this document as a lien and encumbrance against any other persons, companies and interests, commercial or non-profit, particularly any companies or

